Electorchemical Etch for High Tin Solder Bumps

Abstract

An aqueous electrochemical etchant for etching metals (16) in the presence of one or more metals (34,36) not to be etched, the etchant including glycerol in the concentration range of 1.30 to 1.70 M, a sulfate compound having a sulfate ion concentration in the range of 0 to 0.5 M, and a phosphate compound having a phosphate ion concentration in the range of 0.1 to 0.5 M.

Fig 6.